

# FDD5670

## 60V N-Channel PowerTrench® MOSFET

### General Description

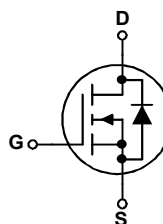
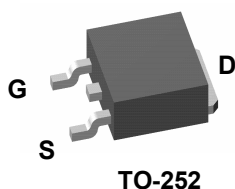
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low  $R_{DS(ON)}$  and fast switching speed. extremely low  $R_{DS(ON)}$  in a small package.

### Applications

- DC/DC converter
- Motor drives

### Features

- 52 A, 60 V  $R_{DS(ON)} = 15\text{ m}\Omega @ V_{GS} = 10\text{ V}$   
 $R_{DS(ON)} = 18\text{ m}\Omega @ V_{GS} = 6\text{ V}$
- Low gate charge
- Fast switching
- High performance trench technology for extremely low  $R_{DS(ON)}$



### Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DSS}$	Drain-Source Voltage	60	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous (Note 3)	52	A
	– Pulsed (Note 1a)	150	
$P_D$	Power Dissipation for Single Operation (Note 1)	83	W
		3.8	
		1.6	
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +175	$^\circ\text{C}$

### Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	1.8	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	40	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1b)	96	$^\circ\text{C/W}$

### Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
FDD5670	FDD5670	13"	16mm	2500 units

**Electrical Characteristics** $T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Drain-Source Avalanche Ratings (Note 2)						
W <sub>DSS</sub>	Drain-Source Avalanche Energy	Single Pulse, V <sub>DD</sub> = 20 V, I <sub>D</sub> = 10A			360	mJ
I <sub>AR</sub>	Drain-Source Avalanche Current				10	A
Off Characteristics						
BV <sub>DSS</sub>	Drain–Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	60			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		53		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 48 V, V <sub>GS</sub> = 0 V			1	μA
I <sub>GSSF</sub>	Gate–Body Leakage, Forward	V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate–Body Leakage, Reverse	V <sub>GS</sub> = –20 V, V <sub>DS</sub> = 0 V			–100	nA
On Characteristics (Note 2)						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2	2.5	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		–6		mV/°C
R <sub>DS(on)</sub>	Static Drain–Source On–Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A V <sub>GS</sub> = 6 V, I <sub>D</sub> = 9 A V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A, T <sub>J</sub> = 125°C		12 14 19	15 18 26	mΩ
I <sub>D(on)</sub>	On–State Drain Current	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 5 V	60			A
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 10 A		27		S
Dynamic Characteristics						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz		2739		pF
C <sub>oss</sub>	Output Capacitance			441		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			182		pF
Switching Characteristics (Note 2)						
t <sub>d(on)</sub>	Turn–On Delay Time	V <sub>DD</sub> = 30 V, I <sub>D</sub> = 1 A, V <sub>GS</sub> = 10 V, R <sub>GEN</sub> = 6 Ω		20	32	ns
t <sub>r</sub>	Turn–On Rise Time			12	24	ns
t <sub>d(off)</sub>	Turn–Off Delay Time			60	95	ns
t <sub>f</sub>	Turn–Off Fall Time			24	38	ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 A, V <sub>GS</sub> = 10 V		52	73	nC
Q <sub>gs</sub>	Gate–Source Charge			10		nC
Q <sub>gd</sub>	Gate–Drain Charge			13		nC
Drain–Source Diode Characteristics and Maximum Ratings						
V <sub>SD</sub>	Drain–Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 3.5 A (Note 2)		0.74	1.2	V

**Notes:**

1.  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.



a)  $R_{\theta JA} = 40^\circ\text{C/W}$  when mounted on a  
1in<sup>2</sup> pad of 2 oz copper



b)  $R_{\theta JA} = 96^\circ\text{C/W}$  when mounted  
on a minimum pad.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width < 300 $\mu\text{s}$ , Duty Cycle < 2.0%

3. Maximum current is calculated as:  $\sqrt{\frac{P_D}{R_{DS(on)}}}$

where  $P_D$  is maximum power dissipation at  $T_C = 25^\circ\text{C}$  and  $R_{DS(on)}$  is at  $T_{J(max)}$  and  $V_{GS} = 10\text{ V}$ . Package current limitation is 21A

## Typical Characteristics

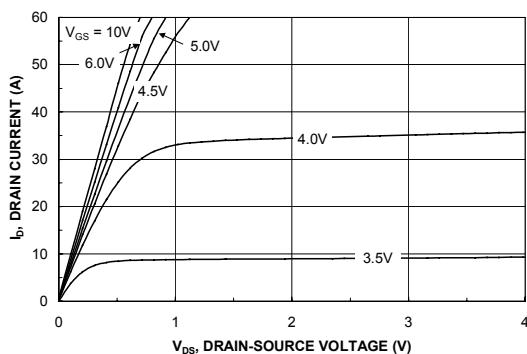


Figure 1. On-Region Characteristics.

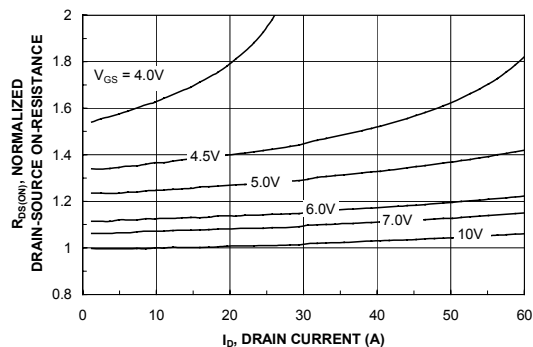


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

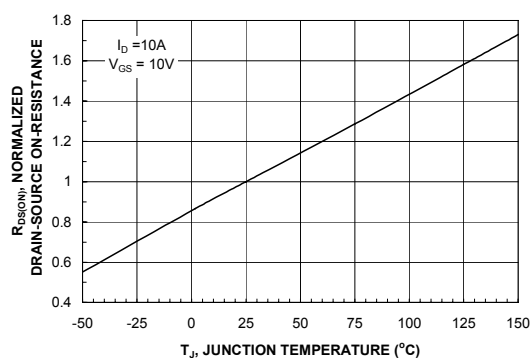


Figure 3. On-Resistance Variation with Temperature.

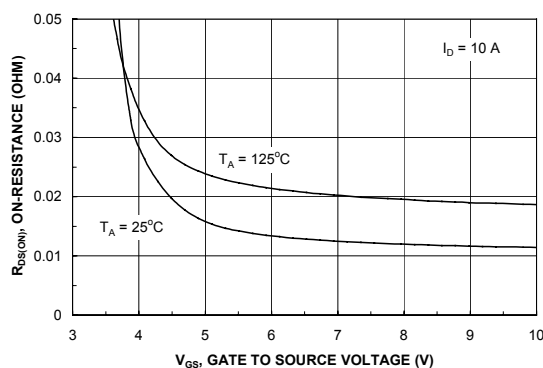


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

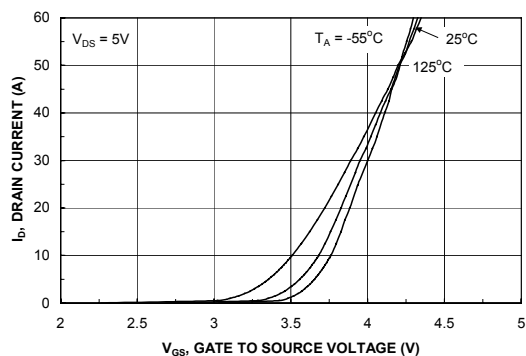


Figure 5. Transfer Characteristics.

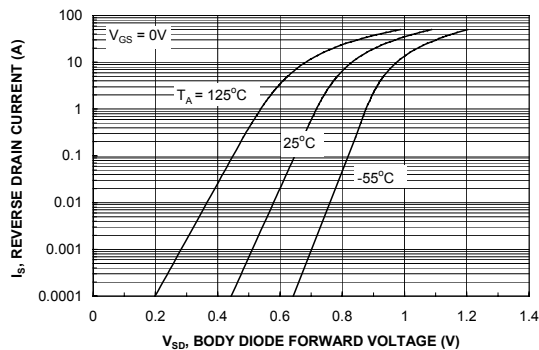


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

## Typical Characteristics

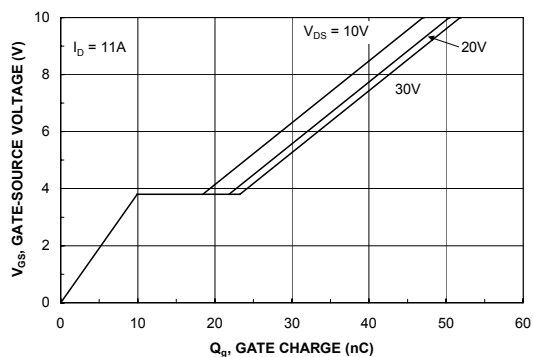


Figure 7. Gate Charge Characteristics.

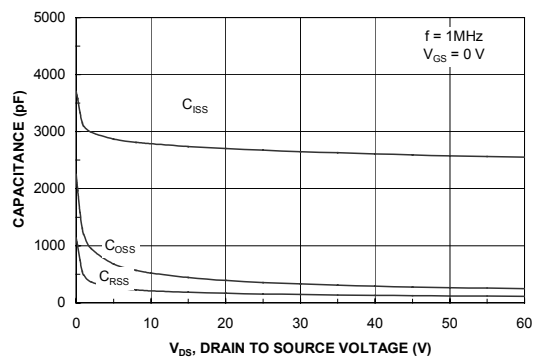


Figure 8. Capacitance Characteristics.

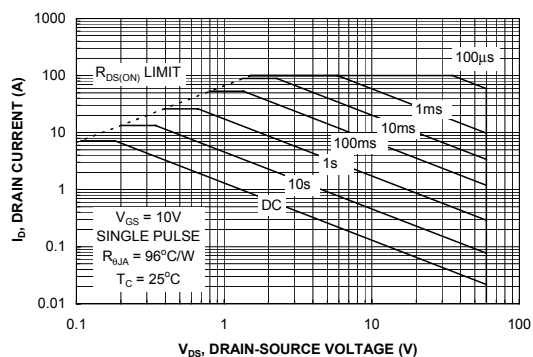


Figure 9. Maximum Safe Operating Area.

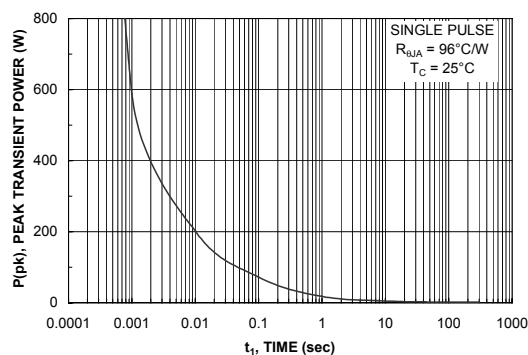


Figure 10. Single Pulse Maximum Power Dissipation.

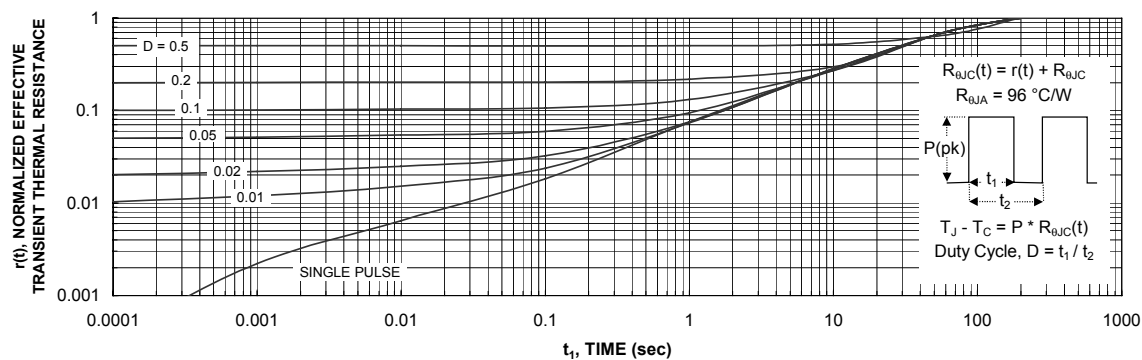




Figure 11. Transient Thermal Response Curve.


Thermal characterization performed using the conditions described in Note 1c.  
Transient thermal response will change depending on the circuit board design.

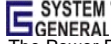

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